**IN THE CLAIMS:**

The following is a complete listing of claims in this application.

6. (currently amended) A method for manufacturing a light emitting diode device comprising the steps of:

preparing a body assembly having a plurality of LED device areas formed by pressing a metal plate;

forming a recess in each of the LED areas;

forming slits in areas arranged on a predetermined line except both side edges, such that each of the areas is divided into a first half body and a second half body;

charging a resin in each slit, so as to insulate the first half body from the second half body in each of the areas;

mounting an LED on the first and second half body at a bottom of ~~the~~ each recess by bumps over the resin in the each slit;

charging a sealing resin under the LED;

securing a transparent sealing plate on the body assembly; and

dividing each area from the body assembly.

7. (previously presented) The method according to claim 6 wherein the recess is formed into a semispherical shape.

8. (previously presented) The method according to claim 6 wherein the recess is formed into an inverted truncated cone.

9. (previously presented) The method according to claim 6 wherein the sealing plate is formed as a convex lens.

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